

Semiconductor Integrated Circuit Device with EMI Prevention Structure

Abstract of the Disclosure

A power lead and a ground lead are connected to corresponding pads of a die through an intra-package wiring substrate. A ground plane is formed in a mold under the intra-package wiring substrate extending along the bottom surface of the mold, and connected to the ground lead. A decoupling capacitor is connected to power wiring and the ground plane to prevent EMI caused by switching noise current generated by the power circuit of the die.

1000 900 800 700 600 500 400 300 200 100 0

Figures

Figure 1: A diagram illustrating the relationship between the variables x and y . The horizontal axis is labeled x and the vertical axis is labeled y . A curve is plotted in the first quadrant, starting from the origin and increasing as x increases. The curve is labeled $y = f(x)$. The area under the curve is shaded and labeled $\int_0^x f(t) dt$. The curve is also labeled $y = f(x)$.